

Title (en)
PROPYLENE RESIN COMPOSITION

Title (de)
PROPYLEN-HARZ-ZUSAMMENSETZUNG

Title (fr)
COMPOSITION DE RÉSINE DE PROPYLÈNE

Publication
EP 3786229 A1 20210303 (EN)

Application
EP 19792956 A 20190424

Priority
• JP 2018083086 A 20180424
• JP 2019017324 W 20190424

Abstract (en)
Disclosed is a propylene-based resin composition comprising more than 15 parts by mass and 40 parts by mass or less of an ethylene/α-olefin copolymer (E1) and 4 to 20 parts by mass of an ethylene/α-olefin/diene copolymer (E2), and comprising also a propylene-based polymer (P1) having an amount of a n-decane-soluble part at 23°C of 5 to 25% by mass, wherein the ethylene content of the n-decane-soluble part is more than 40% by mass and 60% by mass or less, a propylene homopolymer (P2) and an inorganic filler (F) [providing that the total amount of the components (P1), (P2), (E1), (E2) and (F) is taken as 100 parts by weight]. The propylene-based resin composition is capable of producing a molded article which is excellent in mechanical properties, unnoticeable flow marks, low gloss.

IPC 8 full level
C08L 53/00 (2006.01); **C08K 3/013** (2018.01); **C08L 23/00** (2006.01); **C08L 23/08** (2006.01); **C08L 23/26** (2006.01)

CPC (source: EP US)
C08K 3/34 (2013.01 - US); **C08L 23/0815** (2013.01 - US); **C08L 23/083** (2013.01 - US); **C08L 23/12** (2013.01 - US); **C08L 23/14** (2013.01 - US); **C08L 53/00** (2013.01 - EP US); **C08L 2203/30** (2013.01 - US); **C08L 2205/02** (2013.01 - EP); **C08L 2205/025** (2013.01 - EP); **C08L 2205/03** (2013.01 - EP); **C08L 2205/035** (2013.01 - EP US)

Designated contracting state (EPC)
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Designated extension state (EPC)
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